

Selective Soldering System ATF SLS 400

- High end selective soldering machine with excellent price-performance ratio



Robust construction, easy accessibility and highly reproducible process parameter are some of the characteristics of the ATF SLS 400. Therefore special attention is paid for the construction of the transport system. Only if the movement of PCB is without any oscillations, reproducible high quality solder joints are possible.

With selective soldering machines it is always important to keep the small nozzle free of dross. Therefore the ducts were redesigned to reduce significantly the chance of dross clogging the nozzle. Because of both, further improvement of the solder joint and reduction of dross, the use of nitrogen is recommended. Locally at the nozzle nitrogen is applied to have maximum advantage but minimum consumption.

A CCD-camera allows to monitor the wave continuously.

The microprocessor control unit allows easy access and storage of all process parameter. Data are edited via the touch panel of the Display. But highlight is the **ODM** Offline Data Management software. This allows to import easily common PCB data and to define the solder joints. Or the PCB could be scanned and the solder joints selected by simple mouse clicking.

High-grade stainless steel is used for the solder pot. Optional ceramic coating is available for lead-free solder or some parts are made from titanium.

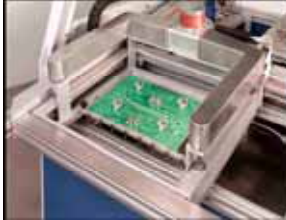
The ATF SLS 400 is designed where medium throughput and a highly reliable machine is required. The ATF SLS 400 offers unequalled performance – price ratio.

Technical description



Machinery

The welded steel base frame is pre-condition for a long-term reliability. Hinged doors allow easy and fast access to the machine; large windows give free sight on the process.



Transport system

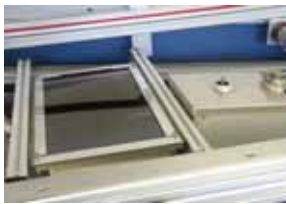
In difference to robot arms is the X-Y-frame of the ATF machine very sturdy and precondition for precise positioning of the PCB on the mini wave. The z-movement is carried out by high precision spindles, which lift the entire X-Y-table with the PCB. The heavy set-up avoids oscillations of the table and allow reproducible movement.

For the movement very quiet micro step motors are used.



Fluxer

The **AHP** (Airless-High-Precision) Fluxer ensures well-defined flux deposition. A high frequency valve controls the volume.



Pre-heating

The ceramic middle-wave infrared (IR) emitter warm up the PCB gently. The panels are covered by Ceran glass. This allows easy cleaning of the pre-heat section. Both, temperature and time can be chosen freely.



Solder pot

High-grade stainless steel is used for the solder pot. Optional ceramic coating is available for lead-free solder. The ducts developed by ATF can be removed easily and reduce significantly the chance of dross clogging the nozzle. The nozzle can be exchanged easily, several diameter are available as standard.



Wave monitoring

A CCD-camera is used to monitor the mini wave, if PC provided.



Control unit

The closed-loop control unit is microprocessor driven and allows the storage of different profiles. The user friendly multilingual software (English, French, German, Italian, Spanish) allows easy access via the touch panel to all parameter like preheat temperature and time, the solder pot temperature and pump speed. The data are shown on a LCD Display.

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